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(12) United States Design Patent
Feng

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(54) **LIGHT EMITTING DIODE CHIP**

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(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/180**

(58) **Field of Classification Search**
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CPC ... H01L 25/167; H01L 25/0753; H01L 27/15; H01L 27/156; H01L 31/02; H01L 33/00; H01L 33/0079; H01L 33/04; H01L 33/08; H01L 33/10; H01L 33/20; H01L 33/38; H01L 33/42; H01L 33/483; H01L 33/486; H01L 24/06; F21K 9/00; F21K 9/30; F21K 9/54; H01J 3/021; H01S 5/34; B82Y 20/00; B82Y 40/00
See application file for complete search history.

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(57) **CLAIM**

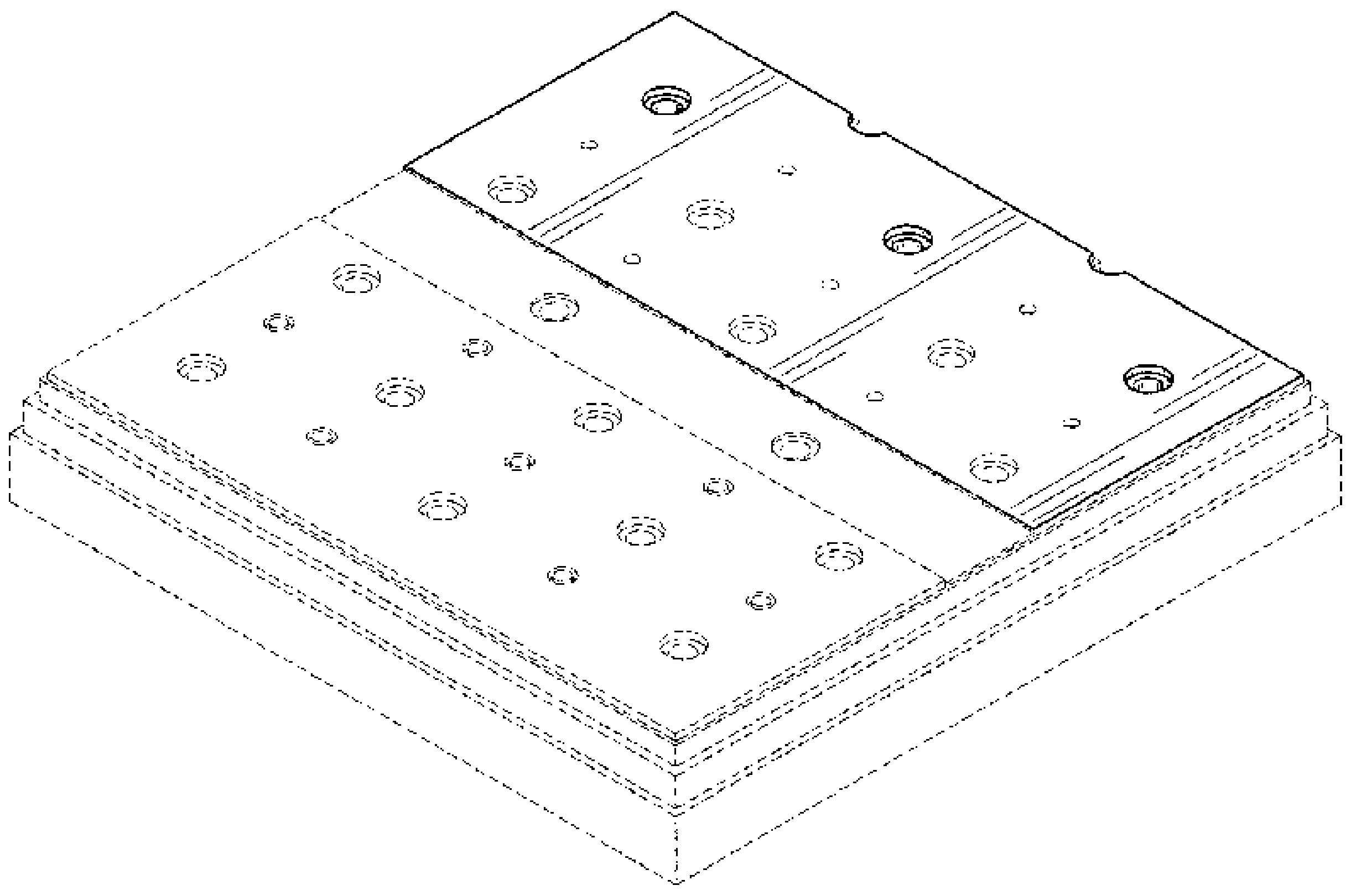
The ornamental design for a light emitting diode chip, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a light emitting diode chip showing of my new design;
FIG. **2** is a front view thereof;
FIG. **3** is a rear view thereof;
FIG. **4** is a left side view thereof;
FIG. **5** is a right side view thereof;
FIG. **6** is a top view thereof; and,
FIG. **7** is a bottom view thereof.

The broken line portions of the light emitting diode chip in FIGS. **1-7** represent unclaimed portions of the design and form no part thereof.

1 Claim, 5 Drawing Sheets



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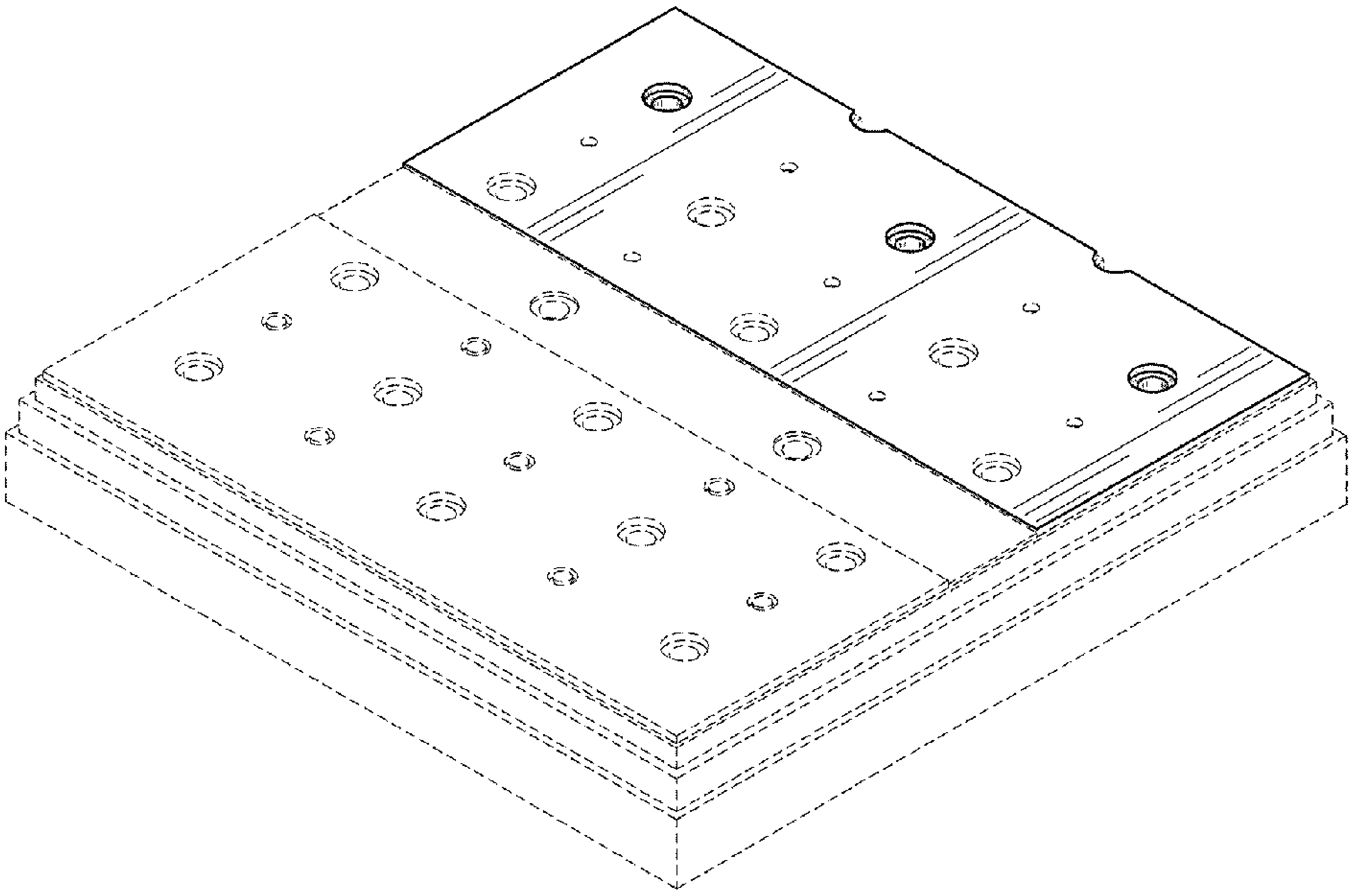

FIG. 1

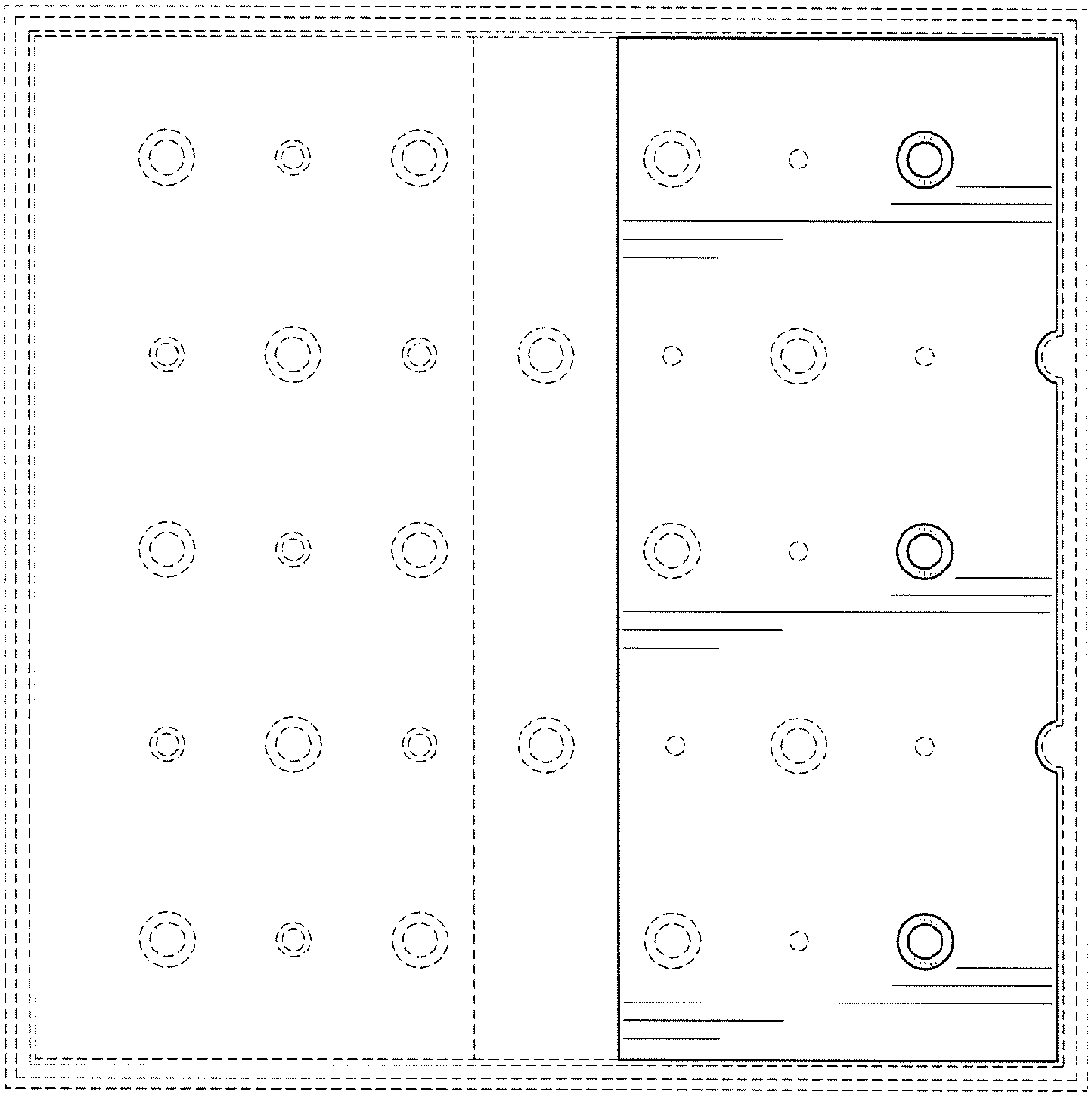

FIG. 2

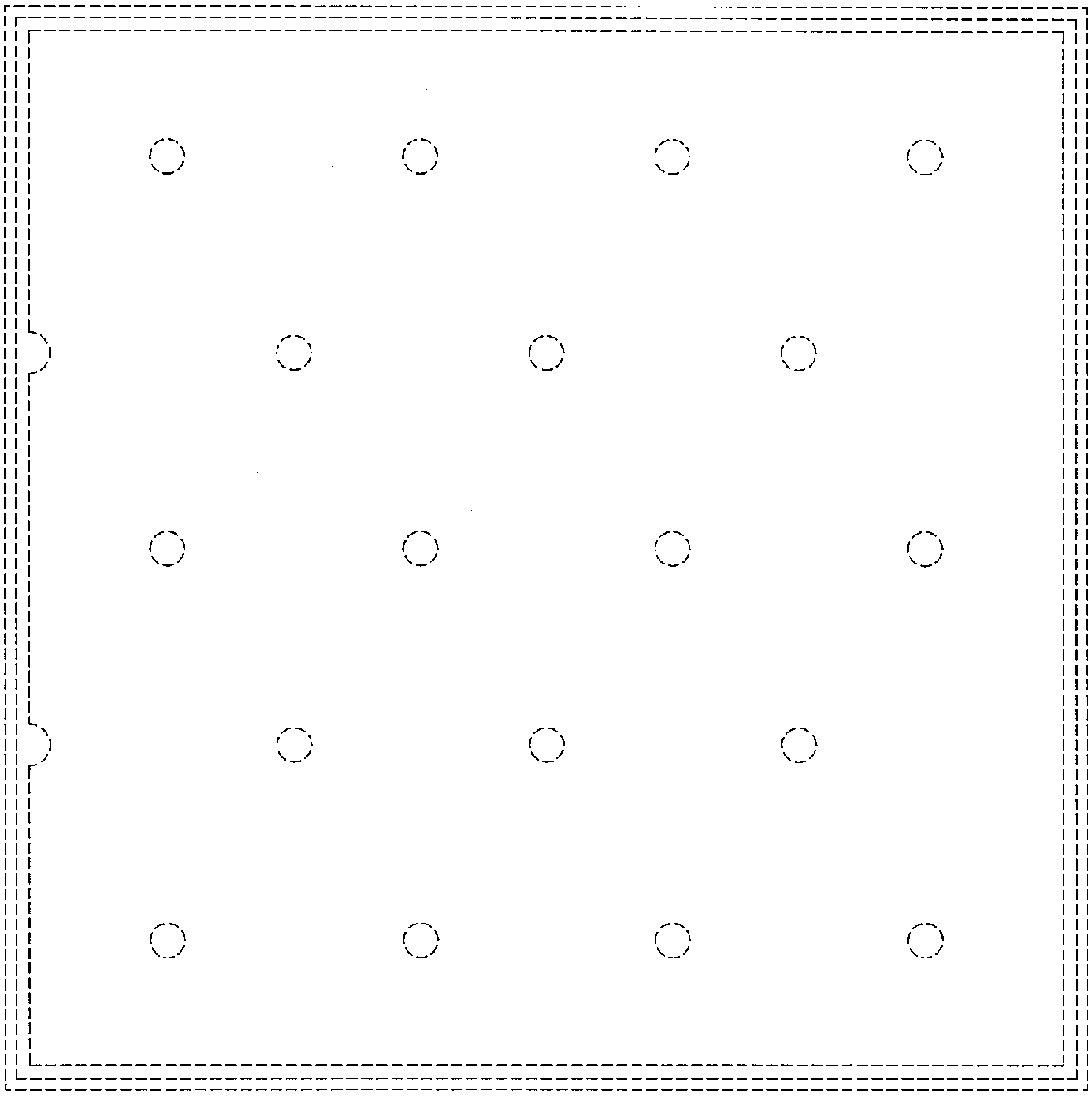

FIG. 3

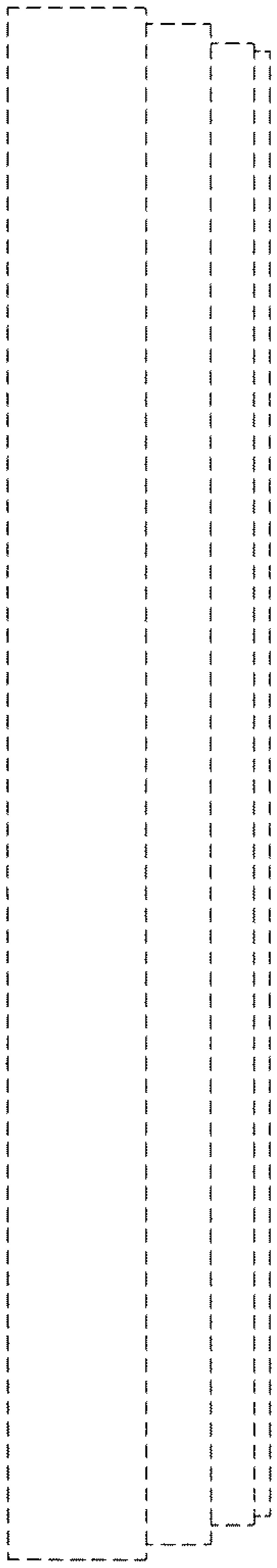

FIG. 4

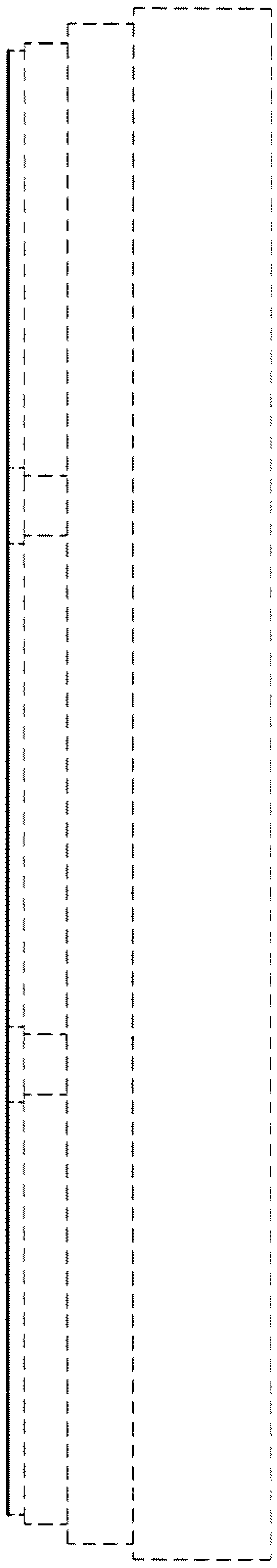

FIG. 5

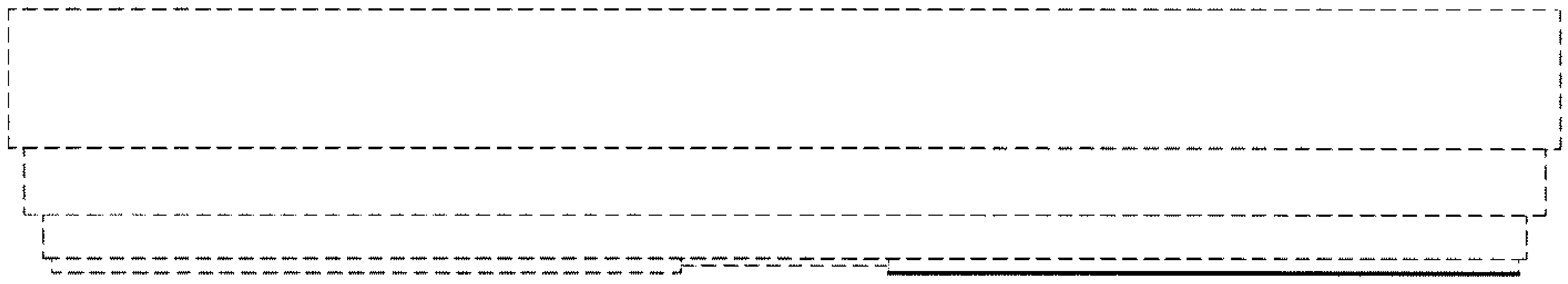

FIG. 6

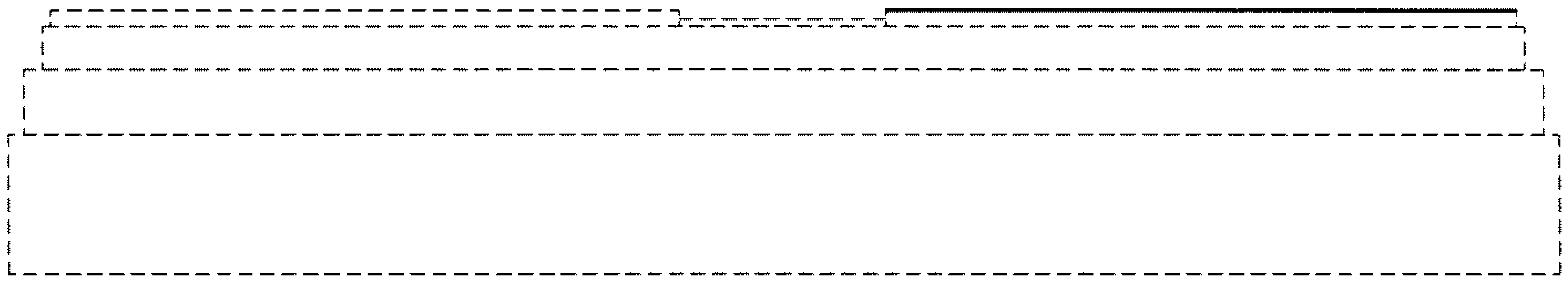

FIG. 7